

**IN THE CLAIMS:**

Please cancel claims 1-26 without prejudice or disclaimer of the subject matter recited therein. Please amend the claims as follows (all claims listed):

27. (New) A flex-print circuit (FPC) attached to at least one bonding pad on a suspension of a head gimbal assembly in a hard disk drive using anisotropic conductive adhesive, comprising:

a base film;

a conductive layer situated below the base film;

an overcoat layer comprising at least two sections situated below the conductive layer, a bottom surface of each section overlapping partially and to be pressed onto a top surface of the bonding pad; and

a conductive structure forming an electric conduit between the conductive layer and the at least one bonding pad, said anisotropic conductive adhesive being disposed at least partially surrounding the conductive structure for bonding the FPC to the at least one bonding pad, wherein the conductive structure comprises a filling completely occupying a space formed by the at least one bonding pad, the conductive layer, and the at least two sections of the overcoat layer.

28. (New) The FPC of claim 27, wherein the filling is less than 10  $\mu\text{m}$  thick.

29. (New) The FPC of claim 27, wherein the filling is about 10 to 38  $\mu\text{m}$  thick.

30. (New) The FPC of claim 27, wherein the filling is thicker than or equal to the overcoat layer.

31. (New) The FPC of claim 27, wherein the filling is thinner than the overcoat layer.

32. (New) A head gimbal assembly (HGA) circuit structure attached to a bonding pad on a suspension of a head gimbal assembly for use in a hard disk drive using anisotropic conductive adhesive, comprising:

a base film;

a conductive layer situated below the base film, a part of said conductive layer attached to the bonding pad using said anisotropic conductive adhesive; and

an overcoat layer situated below a portion of the conductive layer, a bottom surface of said overcoat layer not overlapping a top surface of the bonding pad.

33. (New) The HGA circuit structure of claim 32, further comprising a conductive ball positioned above the bonding pad forming an electric conduit between the conductive layer and the bonding pad.

34. (New) The HGA circuit of claim 33, wherein the conductive ball comprises gold.

35. (New) The HGA circuit structure of claim 32, wherein the anisotropic conductive adhesive comprises anisotropic conductive film.

36. (New) The HGA circuit structure of claim 32, wherein a portion of said conductive layer is bonded to the top surface of the bonding pad directly using said anisotropic conductive adhesive.

37. (New) A method for bonding a flex-print circuit to a suspension in a head gimbal assembly, comprising the steps of:

Forming a conductive structure between a bonding pad and a conductive layer of the flex-print circuit; and

Bonding the conductive layer to the bonding pad via the conductive structure

using anisotropic conductive adhesive.

38. (New) The method of claim 37, wherein the anisotropic conductive adhesive comprises anisotropic conductive film.

39. (New) The method of claim 37, wherein the conductive structure comprises a gold ball.

40. (New) The method of claim 37, wherein the conductive structure comprises a solid conductive material filling.

41. (New) The method of claim 39, wherein the gold ball is formed using stud bump bonding (SBB).

42. (New) A flex-print circuit (FPC) attached to a bonding pad, comprising:  
a conductive layer, in said flex print circuit, bonded to the bonding pad using anisotropic conductive adhesive; and  
a conductive bump lodged between the conductive layer and the bonding pad.

43. (New) The FPC of claim 42, wherein the conductive bump comprises gold.

44. (New) The FPC of claim 42, further comprising an overcoat layer positioned below the conductive layer.

45. (New) The FPC of claim 44, wherein the overcoat layer comprises two sections separated by a plating of conductive material, each of said two sections overlapping an end of a top surface of the bonding pad.

46. (New) The FPC of claim 44, wherein the overcoat layer does not overlap the bonding pad.

47. (New) The FPC of claim 42, wherein the anisotropic conductive adhesive comprises anisotropic film.

48. (New) A bonding device adapted for attachment to a bonding pad with an anisotropic conductive adhesive, the bonding device comprising:

a base film;

a conductive layer having a first side and a second side wherein a first side of the conductive layer is attached to the base film;

an overcoat layer attached to a first portion of a second side of the conductive layer; and

a conductive element attached to a second portion of the second side of the conductive layer wherein the conductive element is adapted to form an electrical conduit between the conductive layer and the attached bonding pad, and the overcoat layer is to press against said bonding pad, wherein the conductive element comprises a filling that completely occupies a space formed by the bonding pad, the conductive layer, and the overcoat layer when the bonding device is attached to the bonding pad.

49. (New) A bonding device according to claim 48 wherein the filling is less than 10  $\mu\text{m}$  thick.

50. (New) A bonding device according to claim 48 wherein the filling is about 10 to 38  $\mu\text{m}$  thick.

51. (New) A bonding device according to claim 48 wherein the filling is thicker than or equal to the overcoat layer.

52. (New) A bonding device according to claim 48 wherein the filling is thinner than the overcoat layer.

53. (New) A bonding device according to claim 48 wherein the base film extends beyond a first end of the conductive layer and wherein the overcoat layer does not overlap any portion of the bonding pad when the bonding device is attached to the bonding pad.